

TOSHIBA Field Effect Transistor Silicon P, N Channel MOS Type (U-MOS IV / U-MOS III)

TPCF8402

Portable Equipment Applications

Motor Drive Applications

DC-DC Converter Applications

Unit: mm

- Low drain-source ON resistance : P Channel $R_{DS(ON)} = 60 \text{ m}\Omega$ (typ.)
N Channel $R_{DS(ON)} = 38 \text{ m}\Omega$ (typ.)
- High forward transfer admittance : P Channel $|Y_{fs}| = 5.9 \text{ S}$ (typ.)
N Channel $|Y_{fs}| = 6.8 \text{ S}$ (typ.)
- Low leakage current : P Channel $I_{DSS} = -10 \text{ }\mu\text{A}$ ($V_{DS} = -30 \text{ V}$)
N Channel $I_{DSS} = 10 \text{ }\mu\text{A}$ ($V_{DS} = 30 \text{ V}$)
- Enhancement-mode
: P Channel $V_{th} = -0.8 \text{ to } -2.0 \text{ V}$ ($V_{DS} = -10 \text{ V}$, $I_D = -1 \text{ mA}$)
N Channel $V_{th} = 1.3 \text{ to } 2.5 \text{ V}$ ($V_{DS} = 10 \text{ V}$, $I_D = 1 \text{ mA}$)

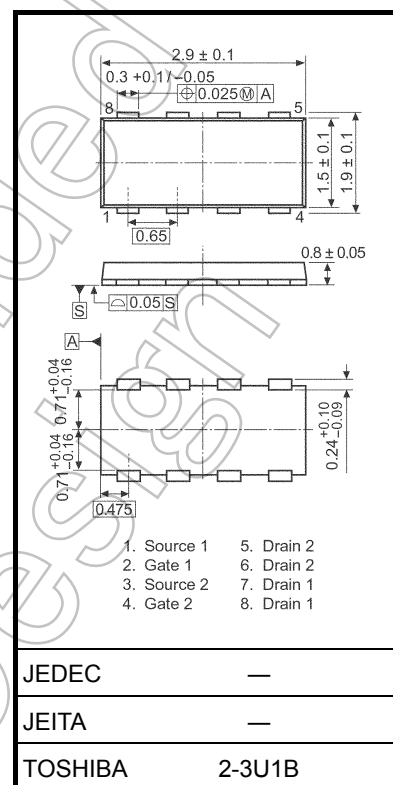
Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

| Characteristics | | Symbol | Rating | | Unit |
|--|---|-----------|------------|----------|------------------|
| Drain-source voltage | | V_{DSS} | -30 | 30 | V |
| Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$) | | V_{DGR} | -30 | 30 | V |
| Gate-source voltage | | V_{GSS} | ± 20 | ± 20 | V |
| Drain current | DC (Note 1) | I_D | -3.2 | 4.0 | A |
| | Pulse (Note 1) | I_{DP} | -12.8 | 16.0 | |
| Drain power dissipation ($t = 5 \text{ s}$) (Note 2a) | Single-device operation (Note 3a) | $P_D(1)$ | 1.35 | 1.35 | W |
| | Single-device value at dual operation (Note 3b) | $P_D(2)$ | 1.12 | 1.12 | |
| Drain power dissipation ($t = 5 \text{ s}$) (Note 2b) | Single-device operation (Note 3a) | $P_D(1)$ | 0.53 | 0.53 | W |
| | Single-device value at dual operation (Note 3b) | $P_D(2)$ | 0.33 | 0.33 | |
| Single pulse avalanche energy (Note 4) | | E_{AS} | 0.67 | 2.6 | mJ |
| Avalanche current | | I_{AR} | -1.6 | 2.0 | A |
| Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5) | | E_{AR} | 0.11 | | mJ |
| Channel temperature | | T_{ch} | 150 | | $^\circ\text{C}$ |
| Storage temperature range | | T_{stg} | -55 to 150 | | $^\circ\text{C}$ |

Note: For Notes 1 to 5, refer to the next page.

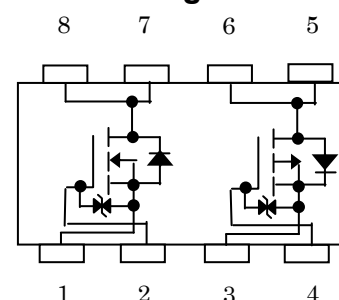
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Handle with caution.



Weight: 0.011 g (typ.)

Circuit Configuration

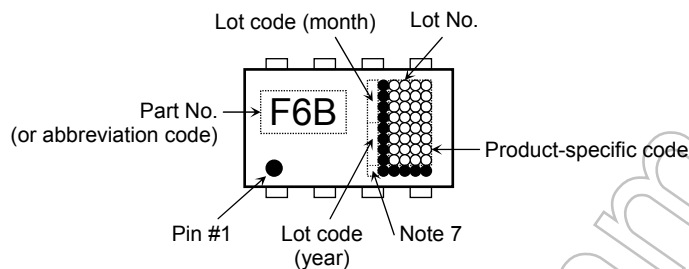


Start of commercial production
2003-02

Thermal Characteristics

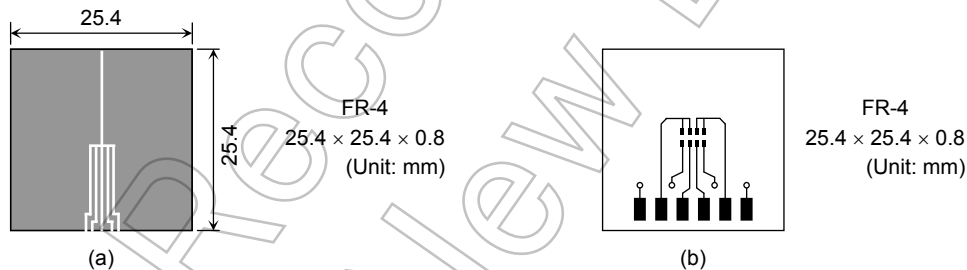
| Characteristics | | Symbol | Max | Unit |
|--|---|---------------------|-------|------|
| Thermal resistance, channel to ambient (t = 5 s) (Note 2a) | Single-device operation (Note 3a) | $R_{th} (ch-a) (1)$ | 92.6 | °C/W |
| | Single-device value at dual operation (Note 3b) | $R_{th} (ch-a) (2)$ | 111.6 | |
| Thermal resistance, channel to ambient (t = 5 s) (Note 2b) | Single-device operation (Note 3a) | $R_{th} (ch-a) (1)$ | 235.8 | °C/W |
| | Single-device value at dual operation (Note 3b) | $R_{th} (ch-a) (2)$ | 378.8 | |

Marking (Note 6)



Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a) (b) Device mounted on a glass-epoxy board (b)



Note 3: a) The power dissipation and thermal resistance values are shown for a single device. (During single-device operation, power is only applied to one device.)

b) The power dissipation and thermal resistance values are shown for a single device. (During dual operation, power is evenly applied to both devices.)

Note 4: P Channel: $V_{DD} = -24 \text{ V}$, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 0.2 \text{ mH}$, $R_G = 25 \Omega$, $I_{AR} = -1.6 \text{ A}$
N Channel: $V_{DD} = 24 \text{ V}$, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 0.5 \text{ mH}$, $R_G = 25 \Omega$, $I_{AR} = 2.0 \text{ A}$

Note 5: Repetitive rating: Pulse width limited by maximum channel temperature.

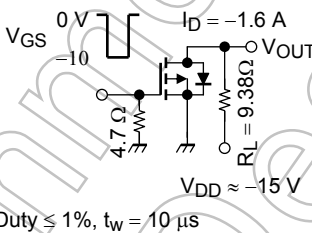
Note 6: "●" on the lower left of the marking indicates Pin 1.

Note 7 A dot marking identifies the indication of product Labels.
Without a dot: [[Pb]]/INCLUDES > MCV
With a dot: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]]

Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product. The RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

P-channel

Electrical Characteristics (Ta = 25°C)

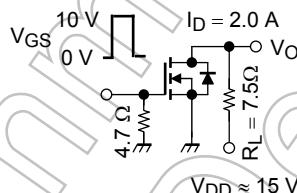
| Characteristics | | Symbol | Test Condition | Min | Typ. | Max | Unit |
|---|---------------|----------------|---|------|------|----------|------------------|
| Gate leakage current | | I_{GSS} | $V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$ | — | — | ± 10 | μA |
| Drain cut-off current | | I_{DSS} | $V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$ | — | — | -10 | μA |
| Drain-source breakdown voltage | | $V_{(BR) DSS}$ | $I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$ | -30 | — | — | V |
| | | $V_{(BR) DSX}$ | $I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$ | -15 | — | — | |
| Gate threshold voltage | | V_{th} | $V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$ | -0.8 | — | -2.0 | V |
| Drain-source ON resistance | | $R_{DS(ON)}$ | $V_{GS} = -4.5 \text{ V}, I_D = -1.6 \text{ A}$ | — | 80 | 105 | $\text{m}\Omega$ |
| | | | $V_{GS} = -10 \text{ V}, I_D = -1.6 \text{ A}$ | — | 60 | 72 | |
| Forward transfer admittance | | $ Y_{fs} $ | $V_{DS} = -10 \text{ V}, I_D = -1.6 \text{ A}$ | 2.9 | 5.9 | — | S |
| Input capacitance | | C_{iss} | $V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | — | 600 | — | pF |
| Reverse transfer capacitance | | C_{rss} | | — | 60 | — | |
| Output capacitance | | C_{oss} | | — | 70 | — | |
| Switching time | Rise time | t_r |  $V_{DD} \approx -15 \text{ V}$ Duty $\leq 1\%$, $t_w = 10 \mu\text{s}$ | — | 5.3 | — | ns |
| | Turn-on time | t_{on} | | — | 12 | — | |
| | Fall time | t_f | | — | 8.4 | — | |
| | Turn-off time | t_{off} | | — | 34 | — | |
| Total gate charge (gate-source plus gate-drain) | | Q_g | $V_{DD} \approx -24 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -3.2 \text{ A}$ | — | 14 | — | nC |
| Gate-source charge 1 | | Q_{gs1} | | — | 1.4 | — | |
| Gate-drain ("miller") charge | | Q_{gd} | | — | 2.7 | — | |

Source-Drain Ratings and Characteristics (Ta = 25°C)

| Characteristics | | Symbol | Test Condition | Min | Typ. | Max | Unit |
|-------------------------|----------------|-----------|---|-----|------|-------|------|
| Drain reverse current | Pulse (Note 1) | I_{DRP} | — | — | — | -12.8 | A |
| Forward voltage (diode) | | V_{DSF} | $I_{DR} = -3.2 \text{ A}, V_{GS} = 0 \text{ V}$ | — | — | 1.2 | V |

N-channel

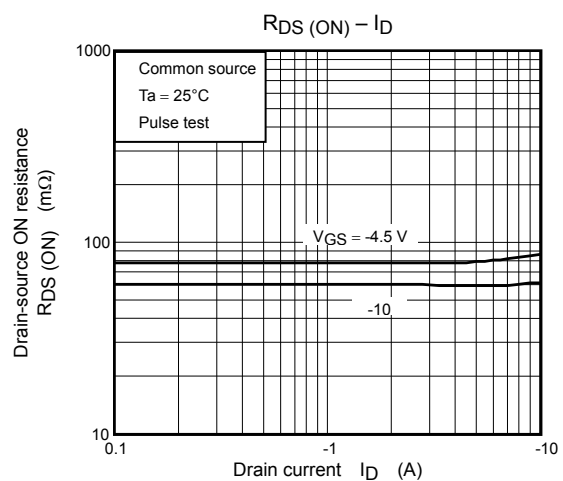
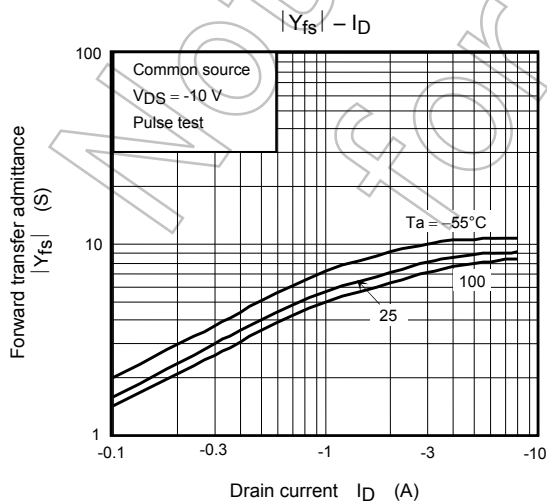
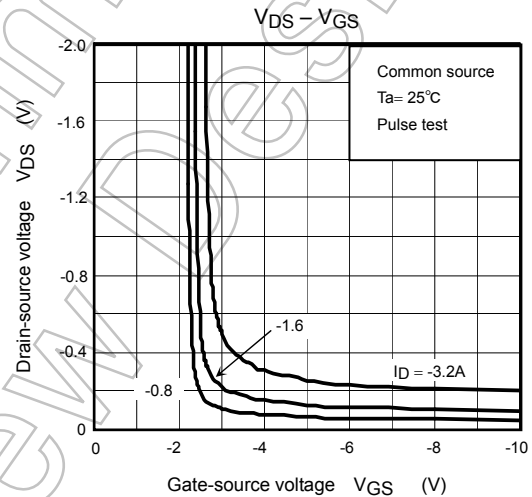
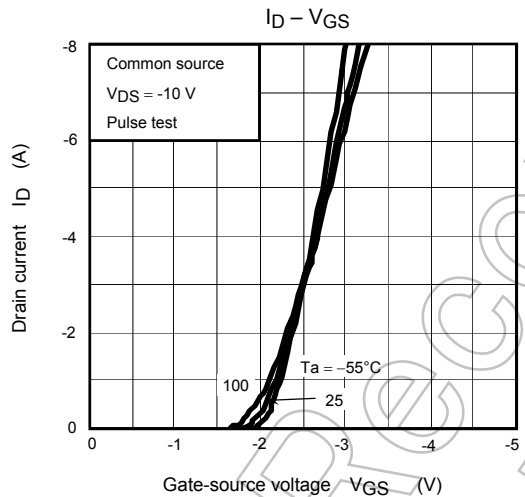
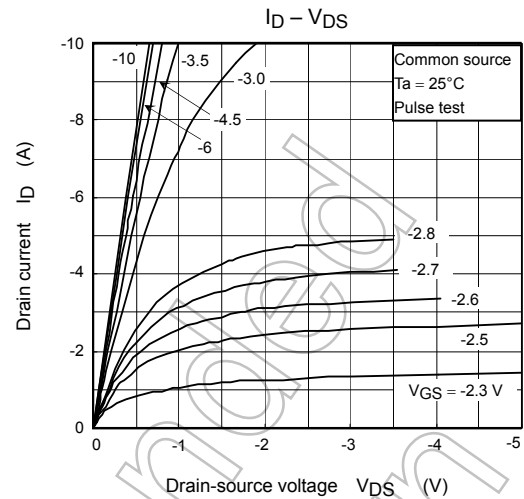
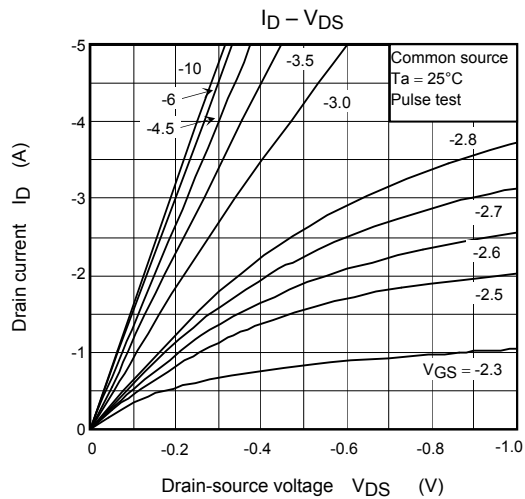
Electrical Characteristics (Ta = 25°C)

| Characteristics | | Symbol | Test Condition | Min | Typ. | Max | Unit |
|---|----------------|---|---|--|------|----------|---------------|
| Gate leakage current | | I_{GSS} | $V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$ | — | — | ± 10 | μA |
| Drain cut-off current | | I_{DSS} | $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$ | — | — | 10 | μA |
| Drain-source breakdown voltage | $V_{(BR) DSS}$ | $I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$ | 30 | — | — | V | |
| | $V_{(BR) DSX}$ | $I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$ | 15 | — | — | | |
| Gate threshold voltage | | V_{th} | $V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$ | 1.3 | — | 2.5 | V |
| Drain-source ON resistance | | $R_{DS(ON)}$ | $V_{GS} = 4.5 \text{ V}, I_D = 2.0 \text{ A}$ | — | 58 | 77 | m Ω |
| | | | $V_{GS} = 10 \text{ V}, I_D = 2.0 \text{ A}$ | — | 38 | 50 | |
| Forward transfer admittance | | $ Y_{fs} $ | $V_{DS} = 10 \text{ V}, I_D = 2.0 \text{ A}$ | 3.4 | 6.8 | — | S |
| Input capacitance | | C_{iss} | $V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | — | 470 | — | pF |
| Reverse transfer capacitance | | C_{rss} | | — | 60 | — | |
| Output capacitance | | C_{oss} | | — | 80 | — | |
| Switching time | Rise time | t_r |  | — | 5.2 | — | ns |
| | Turn-on time | t_{on} | | — | 8.3 | — | |
| | Fall time | t_f | | — | 4.0 | — | |
| | Turn-off time | t_{off} | | Duty $\leq 1\%$, $t_w = 10 \mu\text{s}$ | — | 22 | |
| Total gate charge (gate-source plus gate-drain) | | Q_g | $V_{DD} \approx 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 4 \text{ A}$ | — | 10 | — | nC |
| Gate-source charge 1 | | Q_{gs1} | | — | 1.7 | — | |
| Gate-drain ("miller") charge | | Q_{gd} | | — | 2.4 | — | |

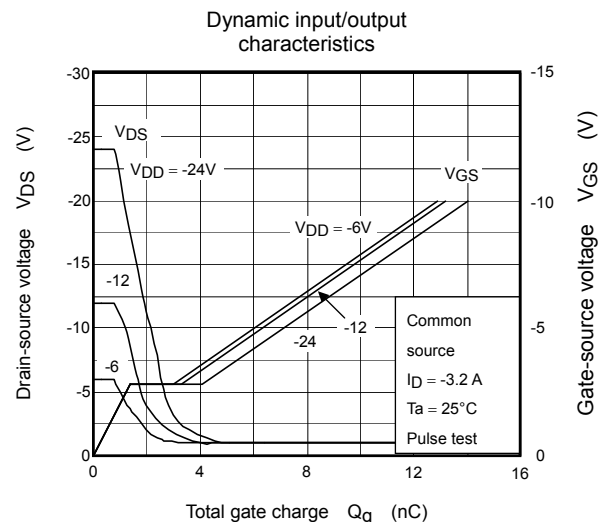
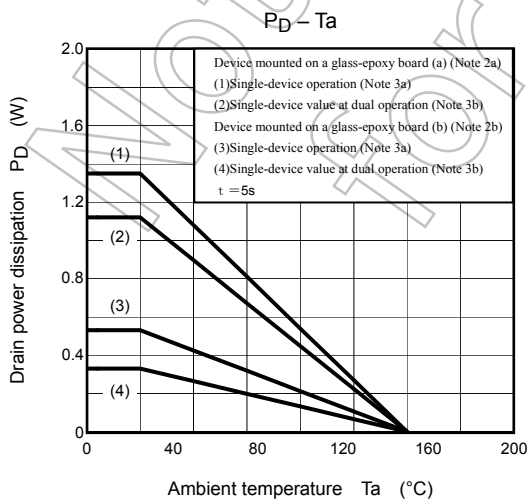
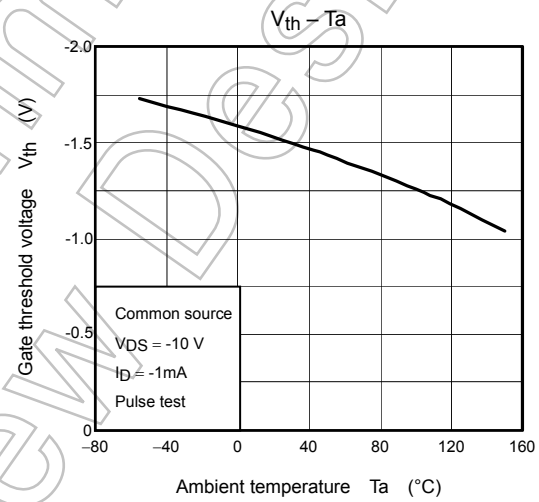
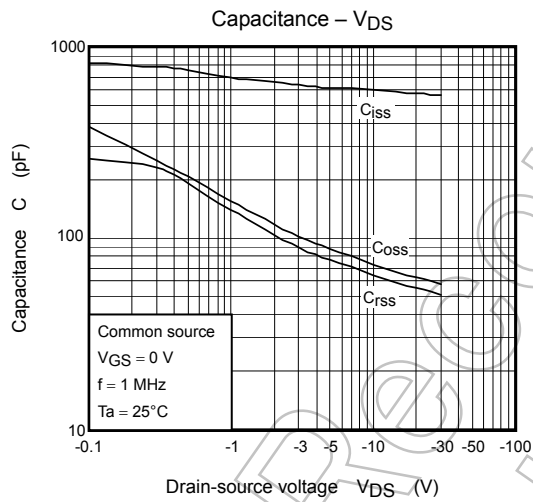
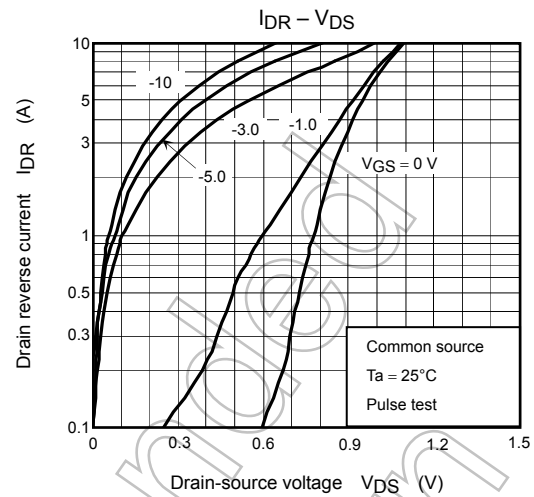
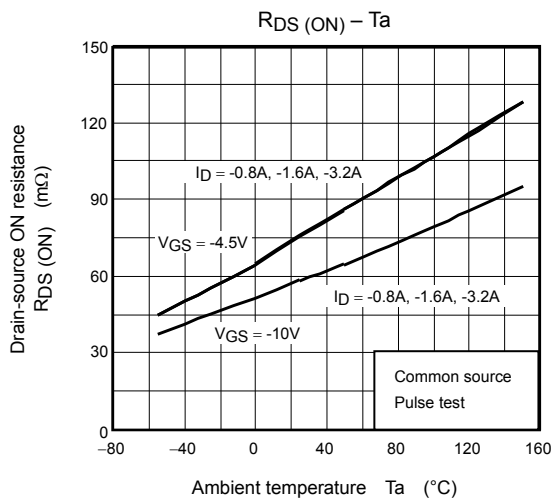
Source-Drain Ratings and Characteristics (Ta = 25°C)

| Characteristics | | Symbol | Test Condition | Min | Typ. | Max | Unit |
|-------------------------|----------------|-----------|--|-----|------|------|------|
| Drain reverse current | Pulse (Note 1) | I_{DRP} | — | — | — | 16.0 | A |
| Forward voltage (diode) | | V_{DSF} | $I_{DR} = 4.0 \text{ A}, V_{GS} = 0 \text{ V}$ | — | — | -1.2 | V |

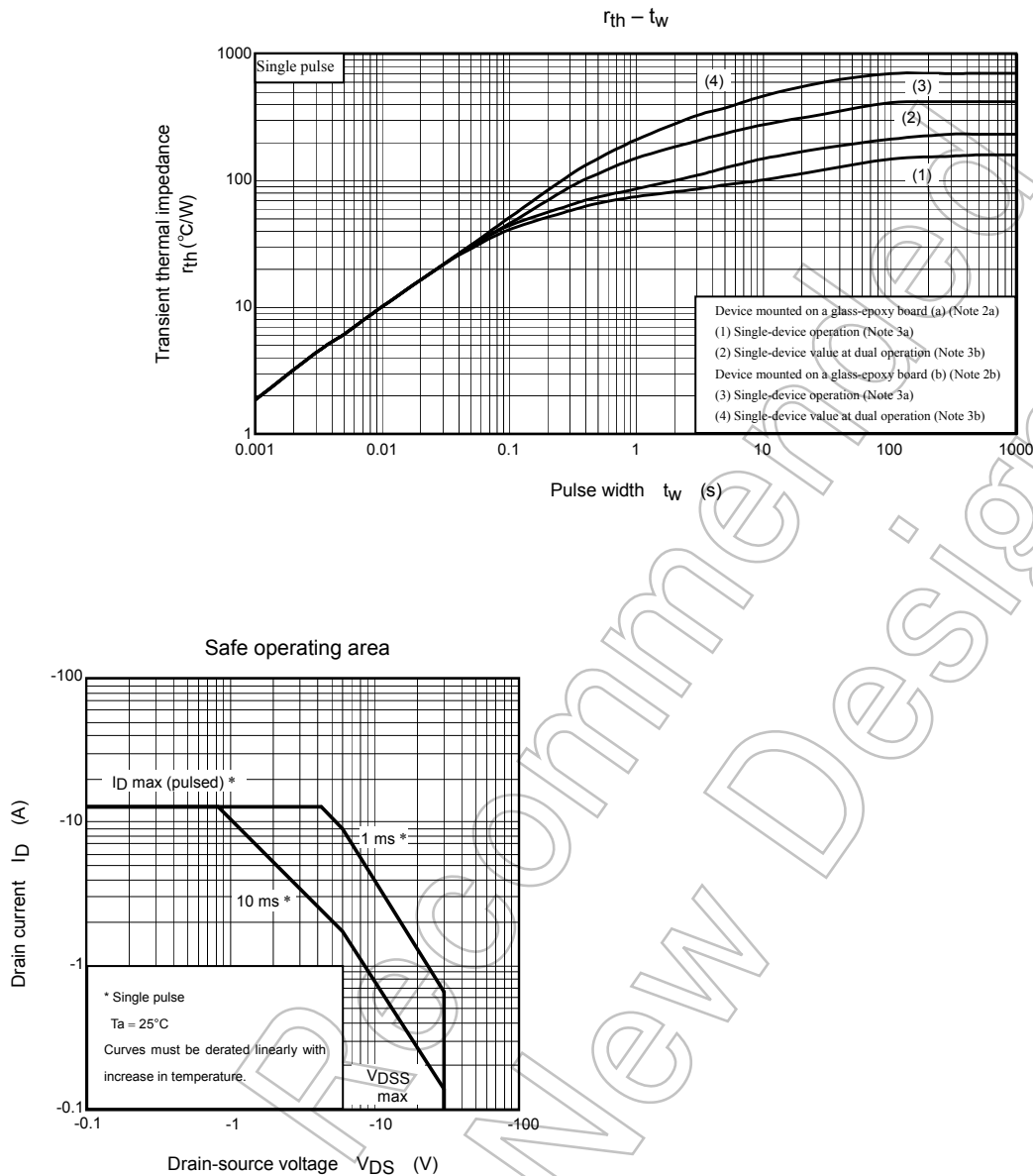
P-channel



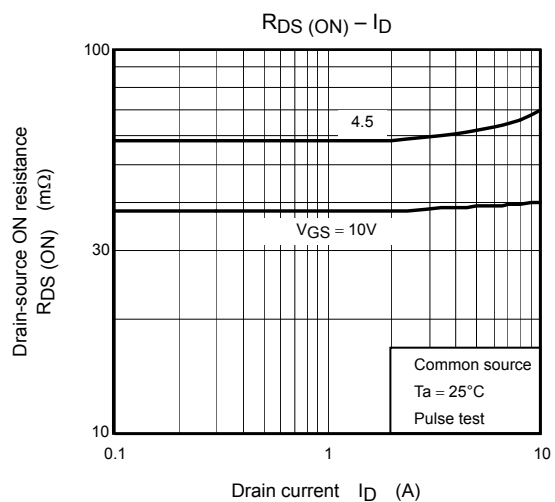
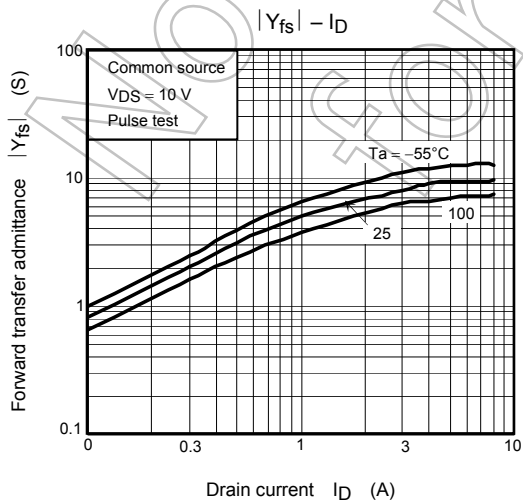
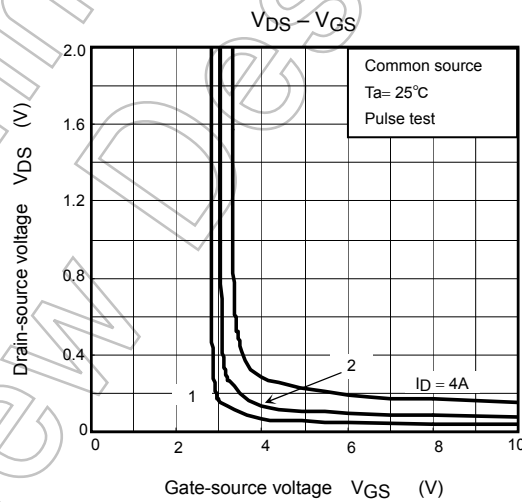
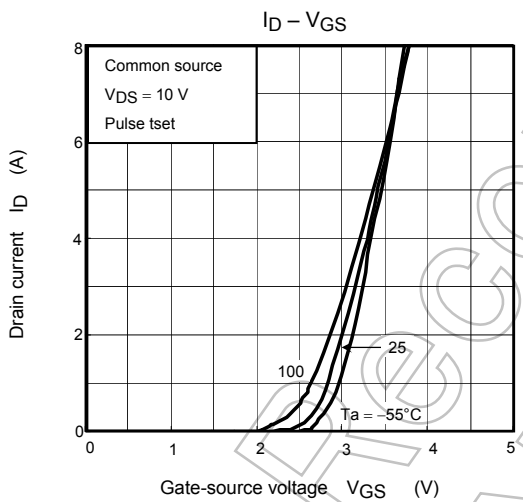
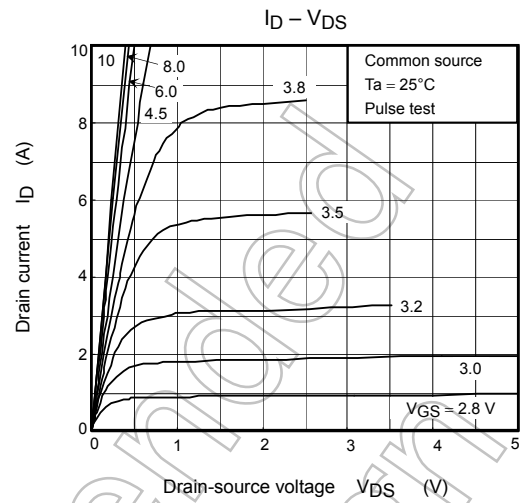
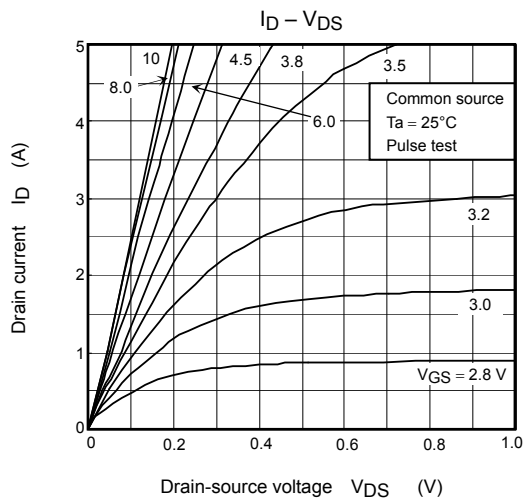
P-channel



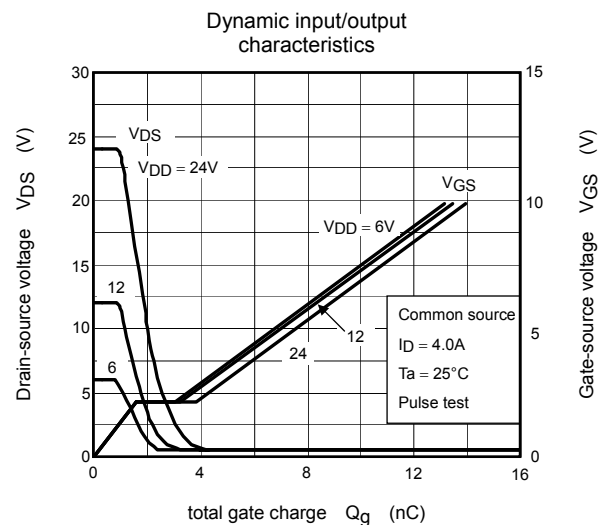
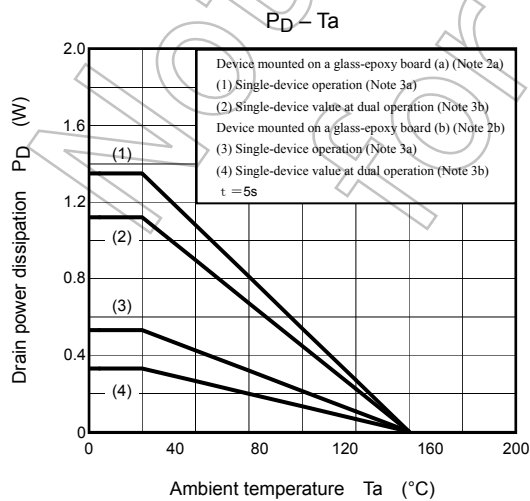
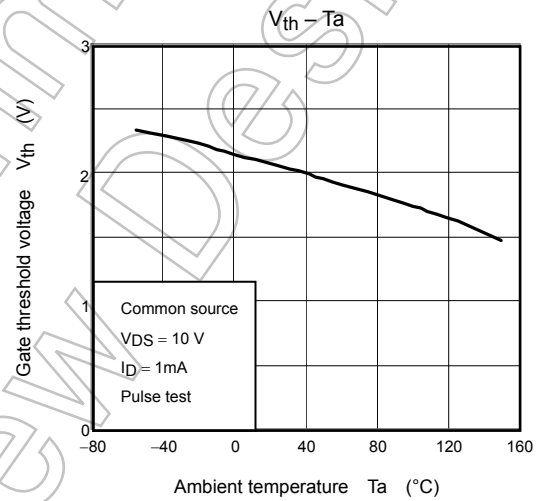
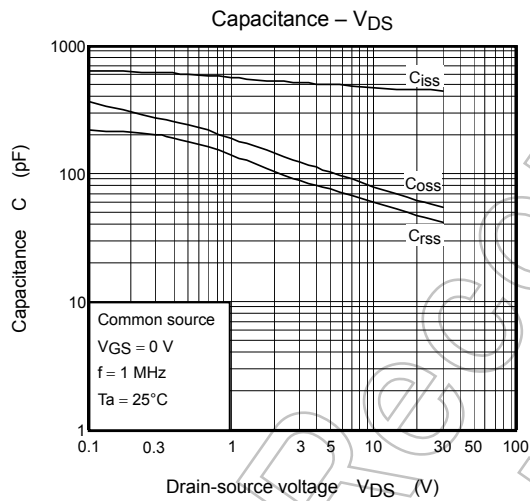
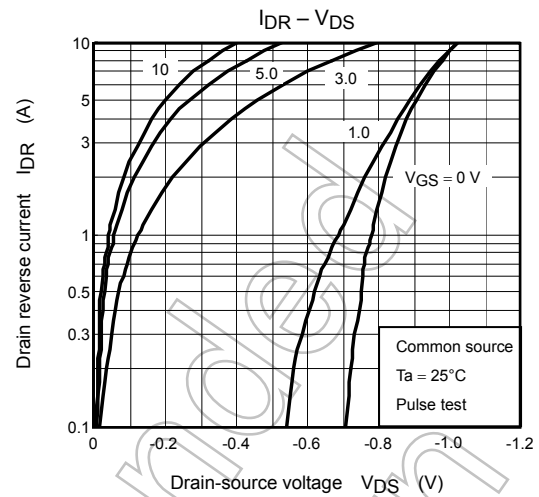
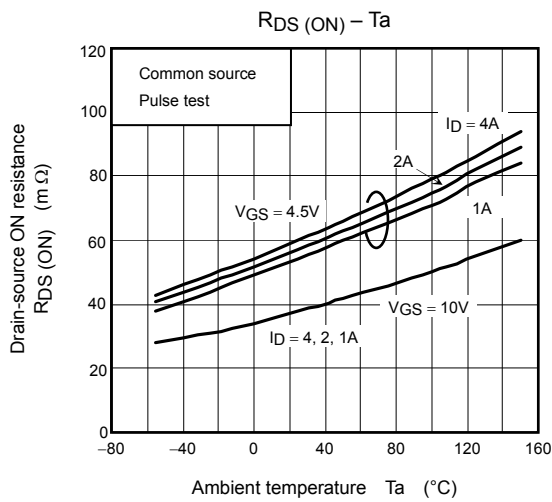
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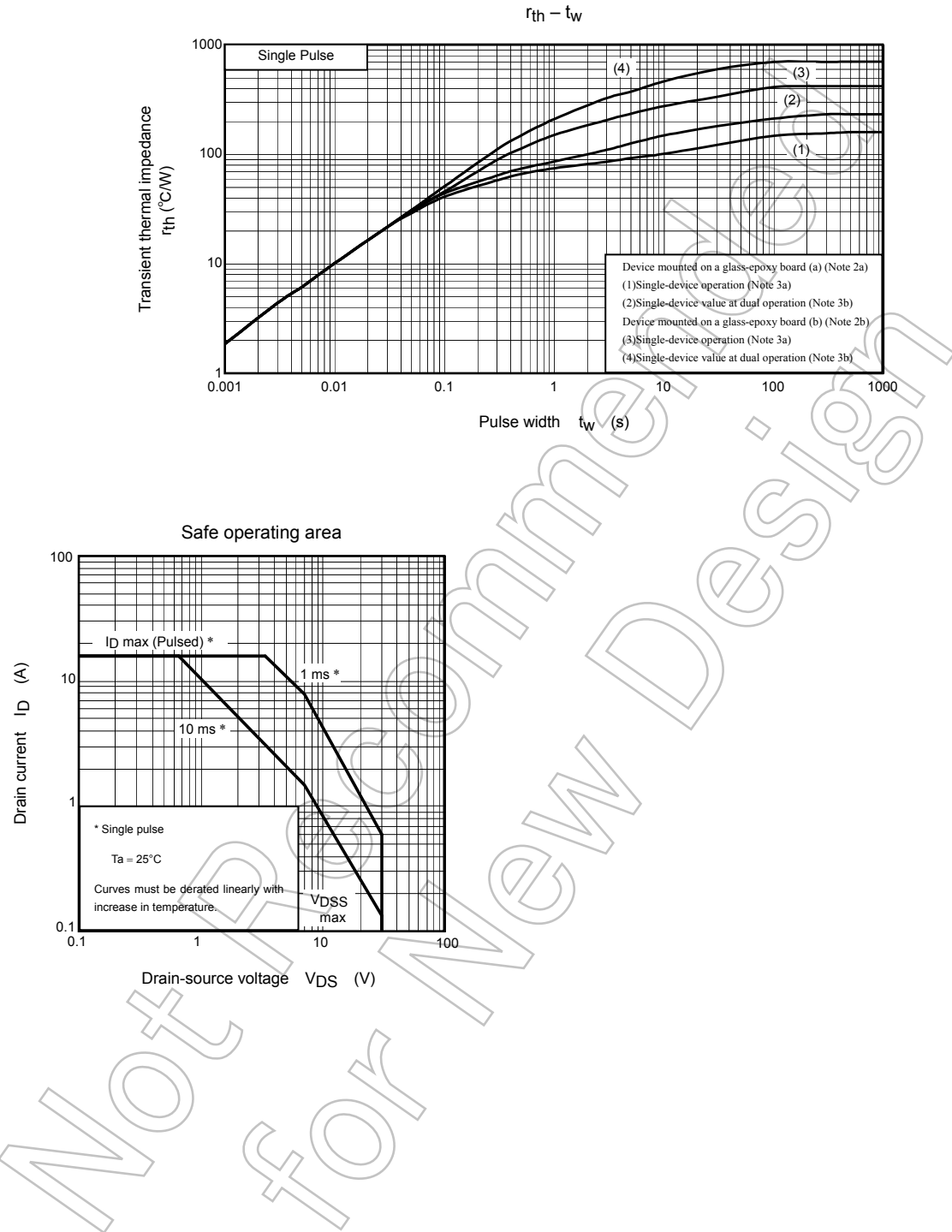
N-channel



N-channel



N-channel



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